

MITSUBISHI HVIGBT MODULES
CM900HC-90H

3rd-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

HIGH POWER SWITCHING USE
 INSULATED TYPE

CM900HC-90H



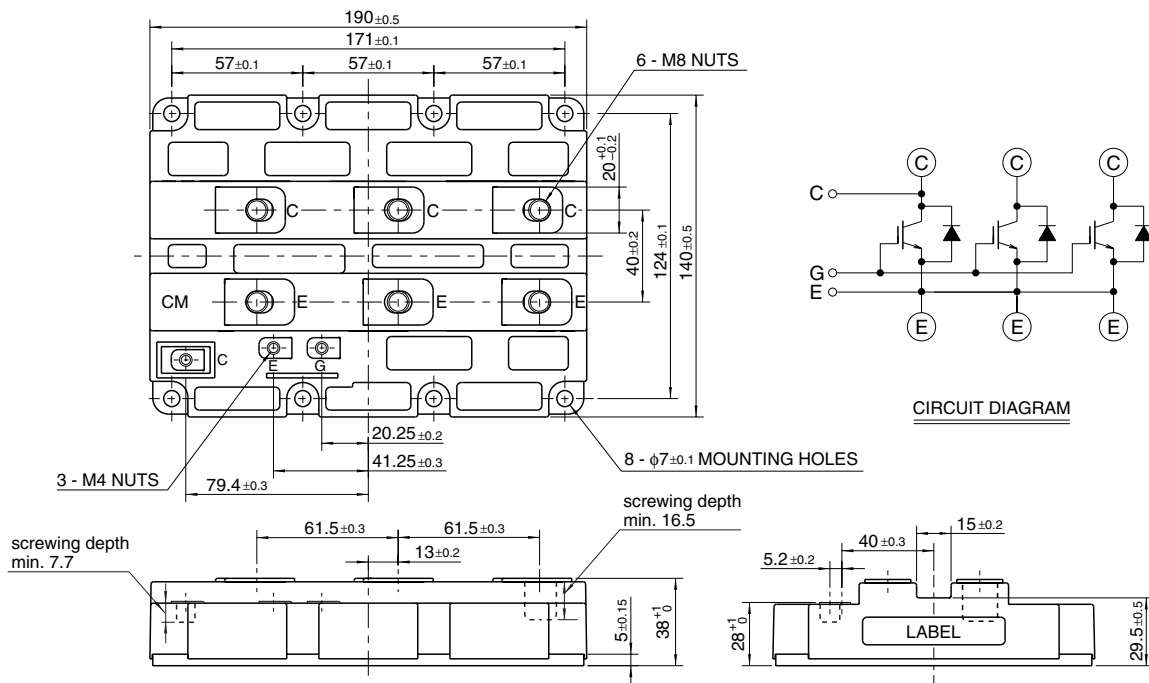
- IC 900 A
- VCES 4500 V
- Insulated Type
- 1-element in a Pack
- AISiC Baseplate

APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



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MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V _{CES}	Collector-emitter voltage	V _{GE} = 0V, T _J = 25°C	4500	V
V _{GES}	Gate-emitter voltage	V _{CE} = 0V, T _J = 25°C	± 20	V
I _C	Collector current	DC, T _c = 100°C	900	A
I _{CM}		Pulse (Note 1)	1800	A
I _E	Emitter current (Note 2)	DC	900	A
I _{EM}		Pulse (Note 1)	1800	A
P _c	Maximum power dissipation (Note 3)	T _c = 25°C, IGBT part	11900	W
V _{iso}	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min.	6000	V
T _J	Junction temperature		-40 ~ +150	°C
T _{op}	Operating temperature		-40 ~ +125	°C
T _{stg}	Storage temperature		-40 ~ +125	°C
t _{psc}	Maximum short circuit pulse width	V _{CC} = 3200V, V _{CE} ≤ V _{CES} , V _{GE} = 15V, T _J = 125°C	10	μs

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit	
			Min	Typ	Max		
I _{CES}	Collector cutoff current	V _{CE} = V _{CES} , V _{GE} = 0V	T _J = 25°C	—	—	5	mA
			T _J = 125°C	—	12	50	
V _{GE(th)}	Gate-emitter threshold voltage	V _{CE} = 10 V, I _C = 90 mA, T _J = 25°C	5.0	6.0	7.0	V	
I _{GES}	Gate leakage current	V _{GE} = V _{GES} , V _{CE} = 0V, T _J = 25°C	—	—	0.5	μA	
C _{ies}	Input capacitance	V _{CE} = 10 V, V _{GE} = 0 V, f = 100 kHz, T _J = 25°C	—	162	—	nF	
C _{oes}	Output capacitance		—	12.0	—	nF	
C _{res}	Reverse transfer capacitance		—	3.6	—	nF	
Q _g	Total gate charge	V _{CC} = 2250 V, I _C = 900 A, V _{GE} = ±15 V, T _J = 25°C	—	15	—	μC	
V _{CE(sat)}	Collector-emitter saturation voltage	I _C = 900 A (Note 4) V _{GE} = 15 V	T _J = 25°C	—	3.45	—	V
			T _J = 125°C	—	3.70	—	
t _{d(on)}	Turn-on delay time	V _{CC} = 2250 V, I _C = 900 A, V _{GE} = ±15 V R _G = 10 Ω, T _J = 125°C, L _S = 100 nH Inductive load	—	—	2.40	μs	
t _r	Turn-on rise time		—	—	1.20	μs	
E _{on(10%)}	Turn-on switching energy (Note 5)		—	4.20	—	J/P	
t _{d(off)}	Turn-off delay time	V _{CC} = 2250 V, I _C = 900 A, V _{GE} = ±15 V R _G = 10 Ω, T _J = 125°C, L _S = 100 nH Inductive load	—	—	6.00	μs	
t _f	Turn-off fall time		—	—	1.20	μs	
E _{off(10%)}	Turn-off switching energy (Note 5)		—	2.50	—	J/P	
V _{EC}	Emitter-collector voltage (Note 2)	I _E = 900 A (Note 4) V _{GE} = 0 V	T _J = 25°C	—	4.80	—	V
			T _J = 125°C	—	4.15	—	
t _{rr}	Reverse recovery time (Note 2)	V _{CC} = 2250 V, I _E = 900 A, V _{GE} = ±15 V R _G = 10 Ω, T _J = 125°C, L _S = 100 nH Inductive load	—	—	1.80	μs	
Q _{rr}	Reverse recovery charge (Note 2)		—	920	—	μC	
E _{rec(10%)}	Reverse recovery energy (Note 2, 5)		—	1.00	—	J/P	

- Note 1. Pulse width and repetition rate should be such that junction temperature (T_J) does not exceed T_{opmax} rating (125°C).
- The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).
- Junction temperature (T_J) should not exceed T_{Jmax} rating (150°C).
- Pulse width and repetition rate should be such as to cause negligible temperature rise.
- E_{on(10%)} / E_{off(10%)} / E_{rec(10%)} are the integral of 0.1V_{CE} x 0.1I_C x dt.

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THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
$R_{th(j-c)Q}$	Thermal resistance	Junction to Case, IGBT part	—	—	10.5	K/kW
$R_{th(j-c)R}$	Thermal resistance	Junction to Case, FWDi part	—	—	21.0	K/kW
$R_{th(c-f)}$	Contact thermal resistance	Case to Fin, $\lambda_{grease} = 1W/m-K$, $D_{(c-f)} = 100 \mu m$	—	6.0	—	K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
M_t	Mounting torque	M8: Main terminals screw	7.0	—	13.0	N·m
M_s		M6: Mounting screw	3.0	—	6.0	N·m
M_t		M4: Auxiliary terminals screw	1.0	—	2.0	N·m
m	Mass		—	1.5	—	kg
CTI	Comparative tracking index		600	—	—	—
d_a	Clearance		19.5	—	—	mm
d_s	Creepage distance		32.0	—	—	mm
L_{PCE}	Parasitic stray inductance		—	10	—	nH
R_{CC+EE}	Internal lead resistance	$T_c = 25^\circ C$	—	0.16	—	mΩ

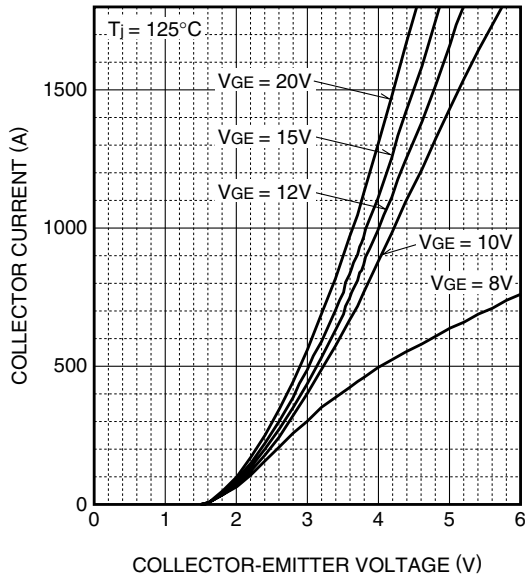
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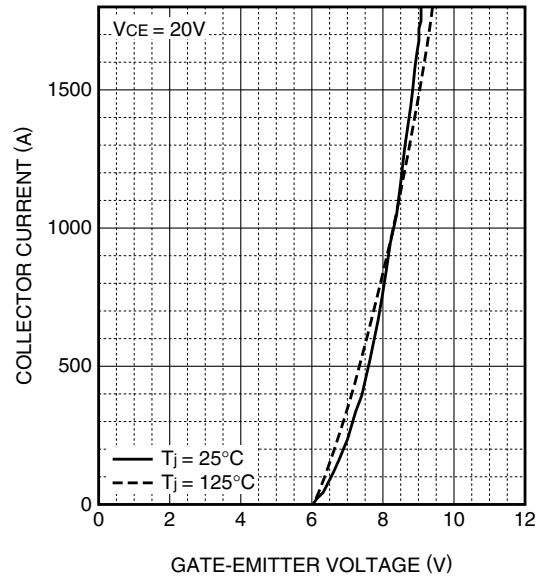
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PERFORMANCE CURVES

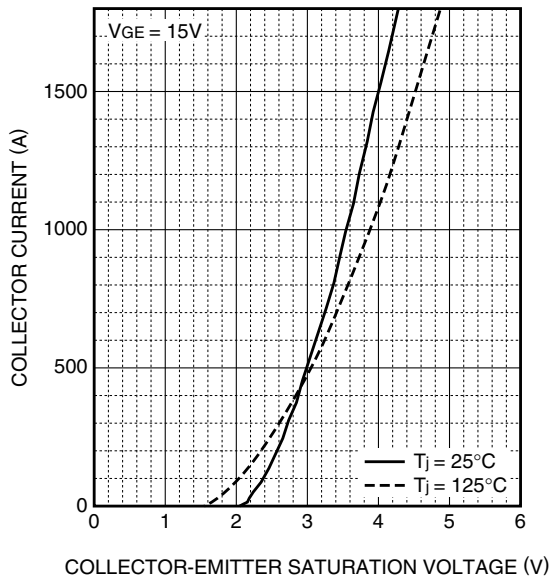
**OUTPUT CHARACTERISTICS
(TYPICAL)**



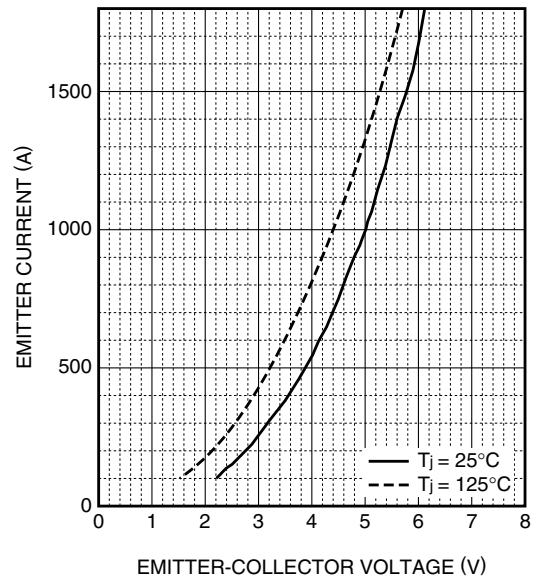
**TRANSFER CHARACTERISTICS
(TYPICAL)**



**COLLECTOR-EMITTER SATURATION
VOLTAGE CHARACTERISTICS
(TYPICAL)**



**FREE-WHEEL DIODE
FORWARD CHARACTERISTICS
(TYPICAL)**

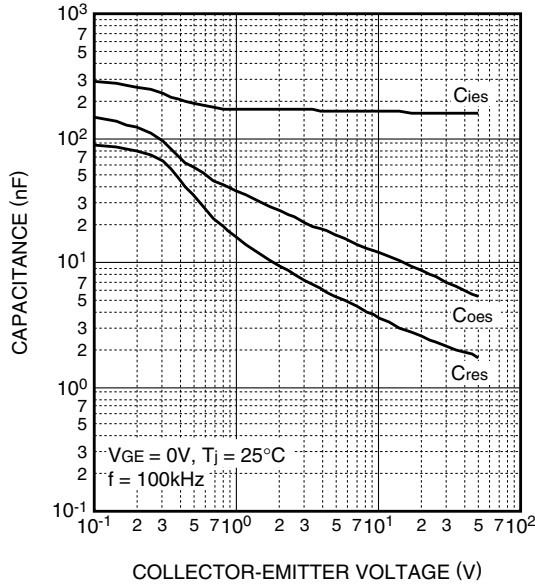


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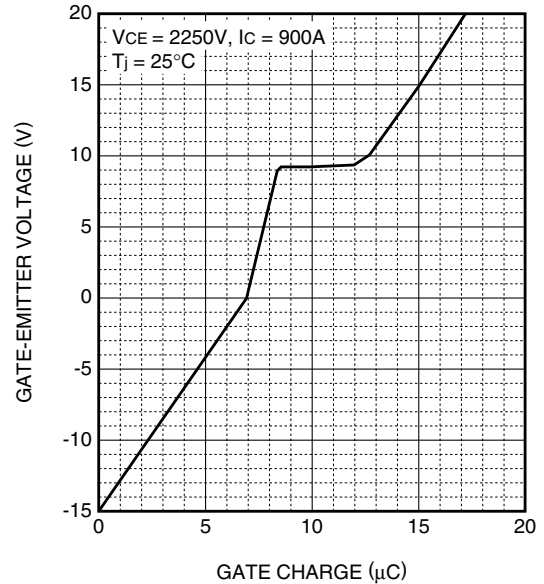
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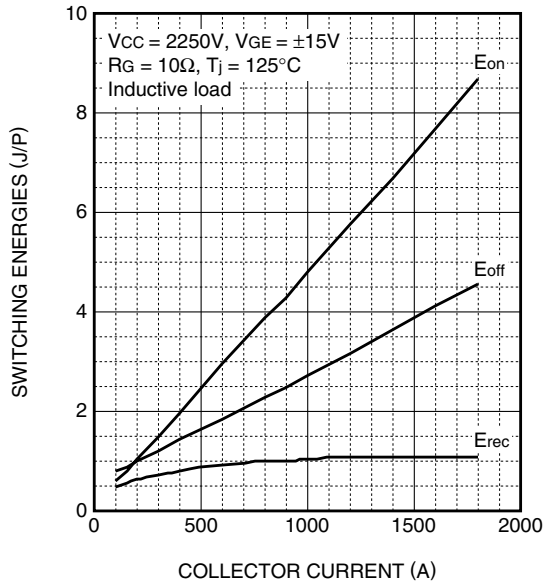
**CAPACITANCE CHARACTERISTICS
(TYPICAL)**



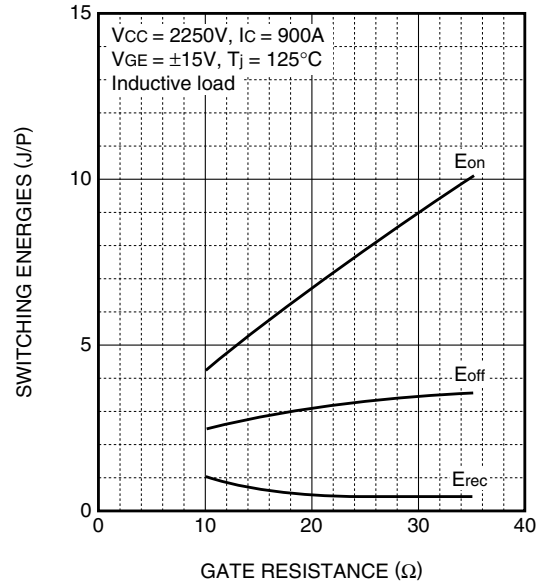
**GATE CHARGE CHARACTERISTICS
(TYPICAL)**



**HALF-BRIDGE SWITCHING ENERGY
CHARACTERISTICS
(TYPICAL)**



**HALF-BRIDGE SWITCHING ENERGY
CHARACTERISTICS
(TYPICAL)**

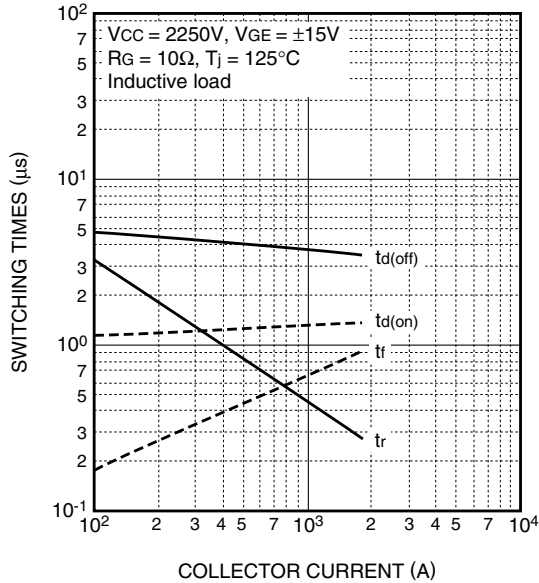


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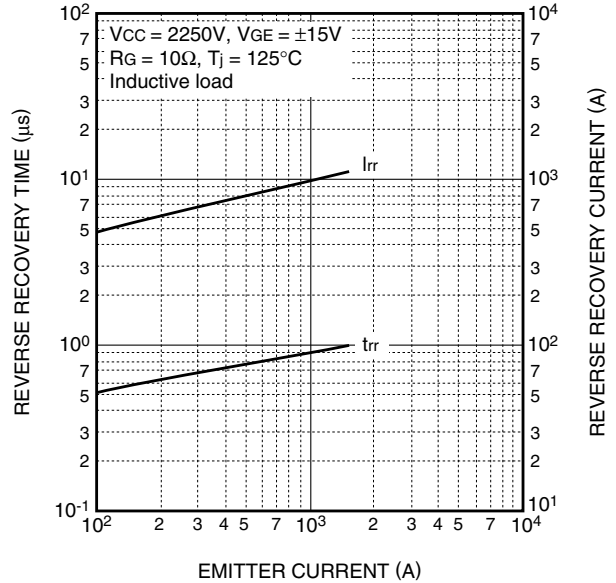
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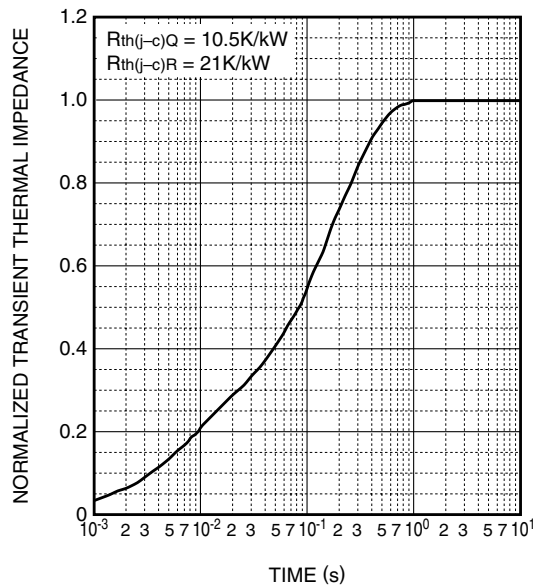
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



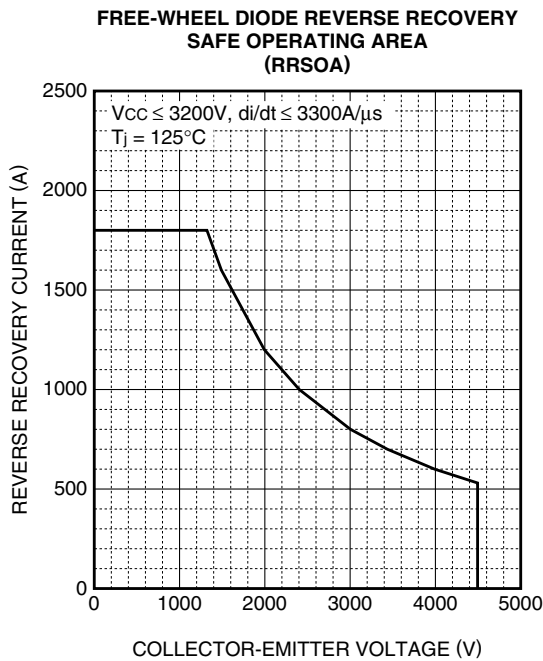
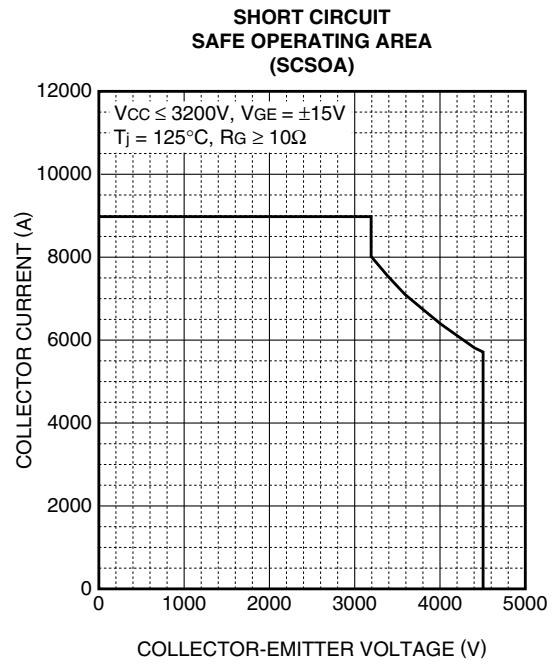
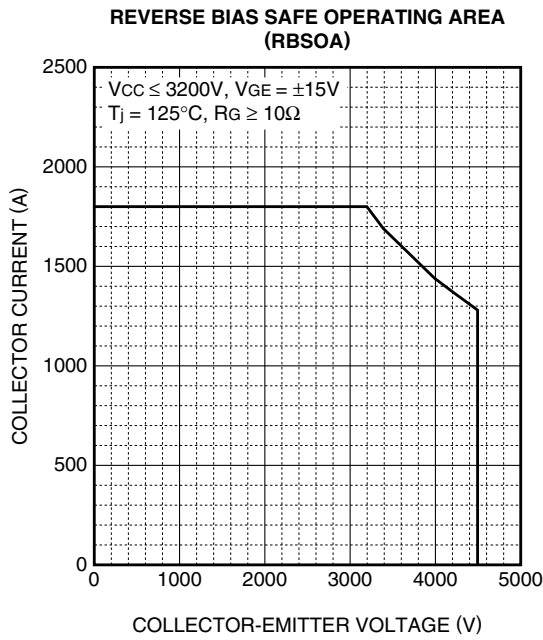
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



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